



Features subject to change without notice



DynaWave
Near Field Communication OEM device
with higher profile



DynaWave Slim
Near Field Communication OEM device
with lower profile

DynaWave & DynaWave Slim

Near Field Communication (NFC) Module

There are more ways to pay and perform digital transactions than ever before. MagTek has the components and peripherals you need for your transaction environment. DynaWave and DynaWave slim meet this growing need. Both products deliver the same electronics but housed in different encasements for great integration flexibility.

Device Overview

The DynaWave Family, MagTek's NFC modules, allow you to add NFC, near-field communication, contactless transactions to your payment solution. NFC allows for faster payments with a quick tap for transaction processing. Whether you need to accept D-PAS[®], PayPass[™], payWave[®], ExpressPay[®], Apple Pay[®], Android Pay[®] or any other bank mobile application that supports contactless, DynaWave is ready.

Applications

Accept contactless payments in almost any environment. DynaWave and DynaWave slim are a perfect fit for contactless payment environments including point of sale applications, point of transaction kiosks, and unattended payment terminals. DynaWave Slim is ideal for environments where lower profile and smaller protrusion is needed in the design.



Call a representative to learn more: 562-546-6400.

Specifications

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Security

DynaWave and DynaWave Slim use 3DES encryption coupled with DUKPT (Derived Unique Key per Transaction) key management to secure your transactional data.

Integration

Designed for easier development efforts, DynaWave and DynaWave Slim are available with either a USB or UART connection. Developers can choose between one or the other depending on the application need and on the profile that best suits their solution. Contact a representative to find the best fit for your application and to request the software developer kits (SDKs) and application programming interfaces (APIs). Some solution designs may include an enclosure for security, protection from environmental factors, or even to add trade dress. The device operates on low power, so no special cooling should be necessary, and the device incorporates a beeper for auditory feedback to cardholders and operators.

Modular Integration

mDynamo is a contact EMV module that connects to a host via USB. It has two optional auxiliary ports (SPI and UART) giving users the flexibility to connect a MagneSafe IntelliHead and/or a DynaWave product, making all three readers into one logical USB device. This modularity allows users to create a solution that meets their specific reading requirements.



Founded in 1972, MagTek is a leading manufacturer of electronic systems for the reliable issuance, reading, transmission and security of cards, checks, PINs and identification documents. Leading with innovation and engineering excellence, MagTek is known for quality and dependability. Its products include secure card reader/authenticators, token generators, EMV contact, contactless and NFC reading devices, encrypting check scanners, PIN pads and distributed credential personalization systems for secure magstripe and EMV enabled cards. These products are used worldwide by financial institutions, retailers, and processors to provide secure and efficient payment and identification transactions. Today, MagTek continues to innovate. Its MagneSafe® Security Architecture leverages strong encryption, secure tokenization, dynamic card authentication, and device/host validation enabling users to assess the trustworthiness of credentials and terminals used for online identification, payment processing, and high-value electronic transactions. MagTek is headquartered in Seal Beach, CA.

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Reference Standards & Certifications

Reference Standards and Certifications
 ISO/IEC 14443 (Type A, Type B)
 EN55024-2010 Information Technology Equipment - Immunity Characteristics
 TDEA (3DES)-CBC using DUKPT
 FCC Title 47 Part 15 Class B
 EMVCo Type Approval – ESD Terminal Evaluation – Test Cases
 IEC 61000-4.2 Edition 2.0 Electromagnetic Compatibility (EMC)
 CE Class B EMC, CE Safety
 UR/CUR UL Recognized, UL 94V-0 Safety of Flammability of Plastic Materials
 MasterCard TOM
 ANSI/IEC 60529-2004 Degrees of Protection Provided by Enclosures
 IPC-A-610-2010 Acceptability of Electronic Assemblies, Class II Assembly
 EU Directive Waste Electrical and Electronic Equipment (WEEE)
 EU Directive Restriction of Hazardous Substances (RoHS)
 California Proposition 65 (California)
 Universal Serial Bus Specification 2.0

Payment methods

NFC contactless / mobile wallets	YES
ISO/IEC 14443 (Type A, Type B) C-6 EMV Contactless, Apple Pay®, Apple VAS®, D-PAS®, ExpressPay®, Google Pay, PayPass™ payWave®, Samsung Pay®	

Reliability and Operation

Tested Operating System(s)	Windows 7, Windows 8.1, Windows 10, Android 4.4.2 and above on devices with USB On-The-Go (OTG) support
Data storage	Non-volatile memory for storage of configuration parameters
Status indicators	Four Blue LEDs

Electrical

Power inputs	Micro USB-B
Power outputs	None
Voltage Requirements	5 VDC
Current Draw	Idle: 70mA Active: Up to 350mA
Wired Connection Types	Micro-USB B, compatible with USB 2.0 and higher; UART

DynaWave Mechanical

Dimensions	3.60 in. W x 2.95 in. H x 1.20 in. D (91.3 mm x 74.9 mm x 30.6 mm)
Weight	2.3 oz. (64g)
Supported Mounting Options	Solution-specific enclosure using nuts on threaded studs/screws

DynaWave Slim Mechanical

Dimensions	3.60 in W x 2.95 in H x 0.70 in D (91.3 mm x 74.9 mm x 17.9 mm)
Weight	2.05 oz (58.0 g)
Supported Mounting Options	Solution-specific enclosure using nuts on threaded studs/screws

Environmental

Ingress Protection:	IP65 Compliant
Operating and storage temp	-22°F to +158°F (-30°C to +70°C)
Operating and storage humidity non-condensing	10% to 90% non-condensing